Surface Mount Superfast Recovery Rectifier

FEATURES:

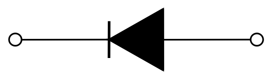
- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Superfast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

Marking

Type number	Marking code
ES5AB	ES5A
ES5BB	ES5B
ES5CB	ES5C
ES5DB	ES5D
ES5EB	ES5E
ES5GB	ES5G
ES5JB	ES5J

Circuit Diagram & Pin Configuration:

SMB/DO-214AA



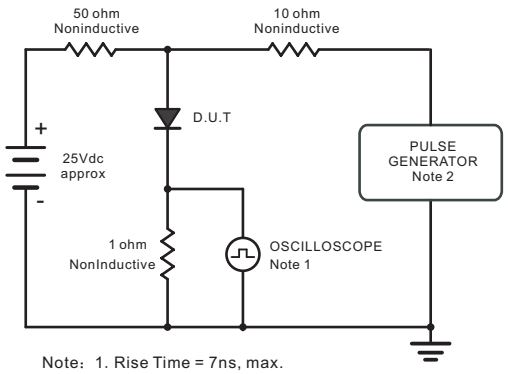
Absolute Maximum Ratings and Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

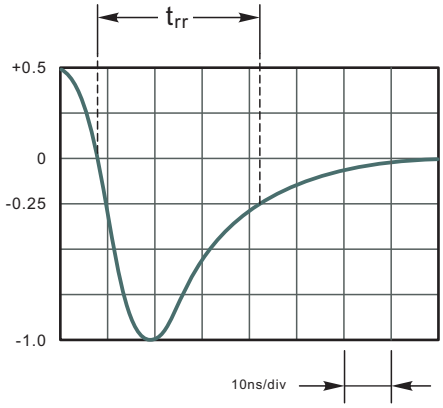
Parameter	Symbols	ES5AB	ES5BB	ES5CB	ES5DB	ES5EB	ES5GB	ES5JB	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	V_{DC}	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current at T_c = 115 °C	$I_{F(AV)}$	5							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	100							A
Maximum Forward Voltage at 5A	V_F	1.0				1.25		1.7	V
Maximum DC Reverse Current at Rated DC Blocking Voltage T_a = 25 °C / T_a =125 °C	I_R	5 100							μA
Typical Junction Capacitance at V_R=4V, f=1MHz	C_j	50							pF
Maximum Reverse Recovery Time [1]	t_{rr}	35							ns
Typical Thermal Resistance [2]	$R_{\theta JA}$ $R_{\theta JC}$	45 15							°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							°C

(1) Measured with I_F = 0.5 A, I_R = 1 A, I_{rr} = 0.25 A.
(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm,22pF.
2. Ries Time =10ns, max.
Source Impedance = 50 ohms.



Set time Base for 10ns/div

Fig.2 Maximum Average Forward Current Rating

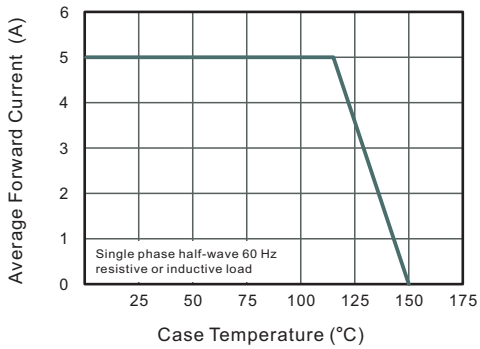


Fig.3 Typical Reverse Characteristics

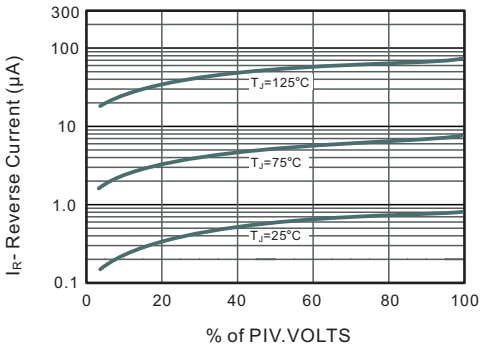


Fig.4 Typical Forward Characteristics

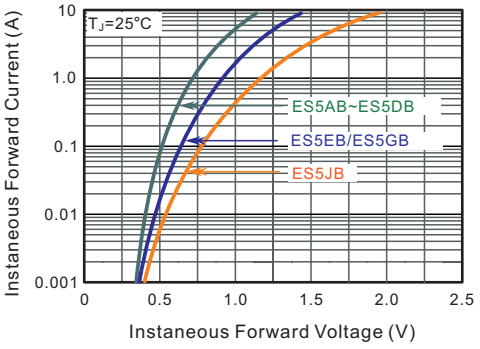


Fig.5 Typical Junction Capacitance

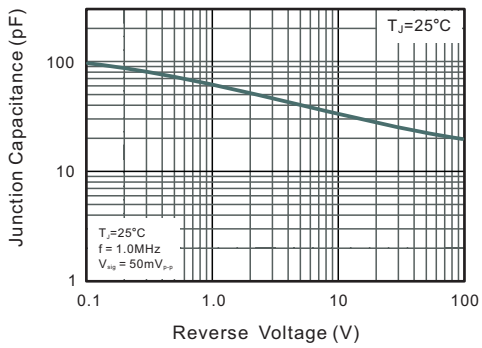
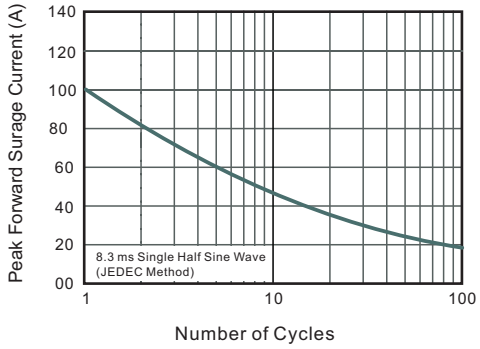
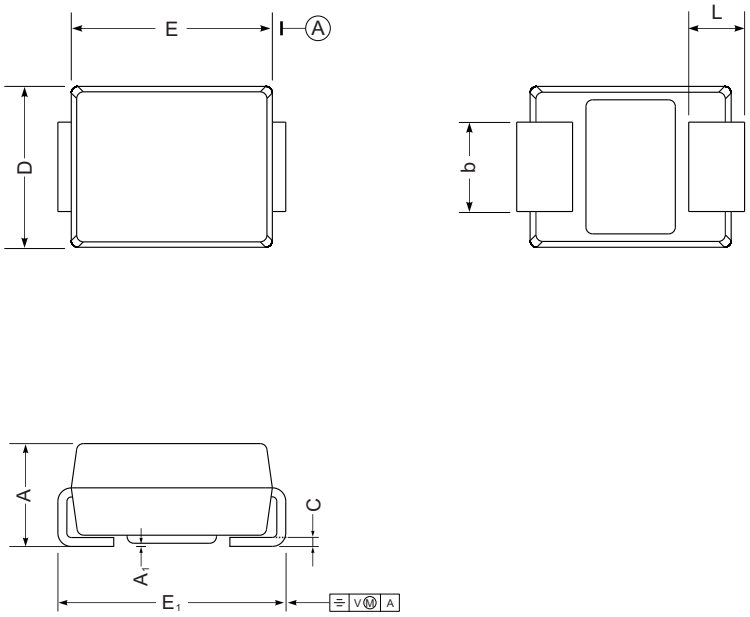


Fig.6 Maximum Non-Repetitive Peak Forward Surage Current



PACKAGE OUTLINE

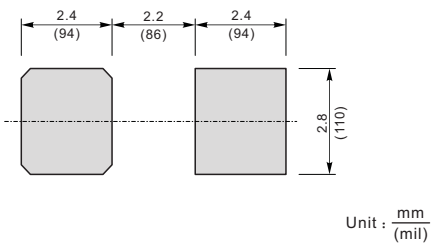
Plastic surface mounted package; 2 leads **SMB/DO-214AA**



SMB mechanical data

UNIT		A	E	D	E_1	A_1	L	C	b
mm	max	2.44	4.70	3.94	5.59	0.20	1.5	0.305	2.2
	min	2.13	4.06	3.3	5.08	0.05	0.8	0.152	1.9
mil	max	96	185	155	220	7.9	59	12	87
	min	84	160	130	200	2.0	32	6	75

The recommended mounting pad size



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